



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification Number:	20260603000.0A	Notification Issued	July 28, 2026
Design Change - PLL enhancement to improve device performance in operation			

Change type(s)
Design
Packing/Shipping/Labeling

Notification Details

Description of Change:	
Texas Instruments is pleased to announce PLL Enhancement to improve device performance in operation for devices listed in the product affected section.	
Reason for Change:	Design Change - PLL Enhancement to improve device performance in operation

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Review the Standard Data Packet for more details on the changes				
Changes to product identification resulting from this PCN:	<table><tr><td>Current</td><td>New</td></tr><tr><td>Die Rev [2P] C</td><td>Die Rev [2P] D</td></tr></table>	Current	New	Die Rev [2P] C	Die Rev [2P] D
	Current	New			
Die Rev [2P] C	Die Rev [2P] D				
	Sample product shipping label (not actual product label): 				

Products Affected:			
MSPM0G1506SPTR	MSPM0G3507SPTR	MSPM0G3506SPMR	MSPM0G1105TRGZR
MSPM0G3507SPMR	MSPM0G3107SDGS28R	MSPM0G3106SDGS20R	MSPM0G1107TYCJR
MSPM0G3505SRGZR	MSPM0G1505SRGER	MSPM0G1106TPMR	MSPM0G3105SDGS20R
MSPM0G1106TRHBR	MSPM0G1106TPTR	MSPM0G3505SPTR	MSPM0G1506SRHBR
MSPM0G1507SRGZR	MSPM0G3505SPMR	MSPM0G1107TDGS28R	MSPM0G1507SRHBR
MSPM0G3105SDGS28R	MSPM0G1505SPTR	MSPM0G1505SDGS28R	MSPM0G1506SPMR
MSPM0G3107SDGS20R	MSPM0G1107TRGZR	MSPM0G1105TPTR	MSPM0G1505SPMR
MSPM0G3506SRGZR	MSPM0G3506SDGS28R	MSPM0G1507SPTR	MSPM0G1106TRGZR
MSPM0G3105SRHBR	MSPM0G3506SPTR	MSPM0G1107TRHBR	MSPM0G1505SRGZR
MSPM0G3506SRHBR	MSPM0G3106SDGS28R	MSPM0G3106SRHBR	MSPM0G1106TYCJR
MSPM0G1107TRGER	MSPM0G1507SDGS28R	MSPM0G1505SRHBR	MSPM0G1507SYCJR
MSPM0G3507SRHBR	MSPM0G1506SDGS28R	MSPM0G1506SYCJR	MSPM0G1107TPTR
MSPM0G3507SRGZR	MSPM0G3505SDGS28R	MSPM0G1507SRGER	MSPM0G1107TPMR
MSPM0G3107SRHBR	MSPM0G1507SRHBR	MSPM0G3507SDGS28R	MSPM0G3505SRHBR
MSPM0G1507SPMR	MSPM0G1506SRGER		

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the contact shown below or your local Field Sales Representative.

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